



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

#8
Election
SDA is
5/7/03

Applicant(s): MURATA et al.

Application No.: 10/091,592

Filed: March 7, 2002

Title: MAGNETIC SENSOR AND
MANUFACTURING METHOD
THEREFOR

Attorney Docket No.: 01-266

Group Art Unit: 2862

Examiner: KINDER, Darrell D

April 30, 2003

RESPONSE TO RESTRICTION/ELECTION REQUIREMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to a Restriction/Election requirement mailed on April 15, 2003 in connection with the above application, Applicant hereby elects Invention I (claims 1 – 5, drawn to a magnetic sensor) without traverse.

Examination of the present application in view of the above election is respectfully requested.

Please charge any necessary fees to Deposit Account 50-1147.

Respectfully submitted,

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Reg. No. 37,701

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A
E. Willis
8-30-02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): MURATA et al.	Atty. Dkt.: 01-266
Serial No.: Unknown	Group Art Unit:
Filed: Concurrently herewith	Examiner:
Title: MAGNETIC SENSOR AND MANUFACTURING METHOD THEREFOR	

Assistant Commissioner for Patents
Washington, D.C. 20231

Date: March 7, 2002

PRELIMINARY AMENDMENT

Sir:

Please enter the following amendment to the specification.

IN THE SPECIFICATION

✓
Please replace the paragraph beginning at page 21 line 26 with the following:

A₁

In order to confirm the effect, different samples (magnetic sensor chips) on which different types of films are formed for the organic film 36 were prepared and experiments were conducted to investigate how cracking would occur. Specifically, for the organic film 36, three samples with different types of films as listed in Table 2, that is, a 0.5 μm thick polyimide film, a 1 μm thick polyimide film and a 0.7 μm thick resist film, were prepared. The chip was fixed to the Cu lead frame 50 through the Ag paste layer 52 by heat treatment (180°C, 60 min), followed by the step of cooling down to a room temperature and further down to -40°C to measure the temperature at which cracking began to occur. The measurement results are shown in Table 2 as "Cracking temperature."